DECLARATION OF INVENTORSHIP AND POWER OF ATTORNEY FOR PATENT APPLICATION

		Docket No.
As a below named inventor, I hereby de	clare that:	
My residence, post office address and cit	izenship are as stated below r	iext to my name.
I believe I am the original, first and sole (if plural names are listed below) of the s	inventor (if only one name is	listed below) or an original, first and joint inventor land for which a patent is sought on the invention IN FABRICATING OF SEMICONDUCTOR
		PACKAGE.
(check one) I is attached hereto.	•	
was filed on	:	
under Application Sc	erial No	
and was amended on		(if applicable).
I hereby state that I have reviewed and un as amended by any amendment referred to	derstand the contents of the a	bove identified specification, including the claims,
acknowledge the duty to disclose to the \$1.56.	Office all information which	is material to Patentability as defined in 37 CFR
hereby claim foreign priority benefits und fisted below and have also identified below before that of the application on which pr	er 35 USC § 119 of any forcig v any forcign application for p iority is claimed.	n application(s) for patent or inventor's certificate atent or inventor's certificate having a filing date
Prior Foreign Application(s)		•
APPLICATION NUMBER TI	COUNTRY	FILING DATE (Day/Month/Year)
Tw 90133149	TAIWAN, ROC	DECEMBER 31, 2001

I hereby claim the benefit under 35 USC § 120 of any United States application (s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed inn the prior United States application in the manner provided by the first paragraph of 35 USC § 112, I acknowledge the duty to disclose to the Office information which is material to patentability as defined in CFR § 1.56 which occurred between the filing date of the prior application and the

APPLICATION NUMBER

FILING DATE
(Day/Month/Year)

STATUS

(Patented, Pending, Abandoued)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

/X0 X4

Address all telephone calls



Address all correspondence to:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 USC 1001, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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